

April 2014

FQA62N25C

N-Channel QFET® MOSFET

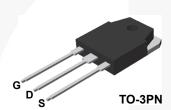
250 V, 62 A, 35 mΩ

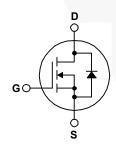
Description

This N-Channel enhancement mode power MOSFET is produced using Fairchild Semiconductor's proprietary planar stripe and DMOS technology. This advanced MOSFET technology has been especially tailored to reduce on-state resistance, and to provide superior switching performance and high avalanche energy strength. These devices are suitable for switched mode power supplies, active power factor correction (PFC), and electronic lamp ballasts.

Features

- + 62 A, 250 V, $R_{DS(on)}$ = 35 m Ω (Max.) @ V_{GS} = 10 V, I_{D} = 31 A
- Low Gate Charge (Typ. 100 nC)
- Low Crss (Typ. 63.5 pF)
- 100% Avalanche Tested





Absolute Maximum Ratings T_C = 25°C unless otherwise noted.

Symbol	Parameter	FQA62N25C	Unit
V_{DSS}	Drain-Source Voltage	250	V
I _D	Drain Current - Continuous (T _C = 25°C)	62	Α
	- Continuous (T _C = 100°C)	39	Α
I _{DM}	Drain Current - Pulsed (Note 1)	248	Α
V_{GSS}	Gate-Source Voltage	± 30	V
E _{AS}	Single Pulsed Avalanche Energy (Note 2)	2300	mJ
I _{AR}	Avalanche Current (Note 1)	62	Α
E _{AR}	Repetitive Avalanche Energy (Note 1)	29.8	mJ
dv/dt	Peak Diode Recovery dv/dt (Note 3)	5.5	V/ns
P_D	Power Dissipation (T _C = 25°C)	298	W
	- Derate above 25°C	2.38	W/°C
T _J , T _{STG}	Operating and Storage Temperature Range	-55 to +150	°C
T _L	Maximum lead temperature for soldering purposes, 1/8" from case for 5 seconds	300	°C

Thermal Characteristics

Symbol	Parameter	FQA62N25C	Unit
$R_{\theta JC}$	Thermal Resistance, Junction-to-Case, Max.	0.42	°C/W
R _{θCS} Thermal Resistance, Case-to-Sink, Typ.		0.24	°C/W
$R_{\theta JA}$	Thermal Resistance, Junction-to-Ambient, Max.	40	°C/W

Package Marking and Ordering Information

Part Number	Top Mark	Package	Packing Method	Reel Size	Tape Width	Quantity
FQA62N25C	FQA62N25C	TO-3PN	Tube	N/A	N/A	30 units

Electrical Characteristics T_c = 25°C unless otherwise noted.

Symbol	Parameter	Test Conditions		Тур.	Max.	Unit
Off Cha	aracteristics					
BV _{DSS}	Drain-Source Breakdown Voltage	$V_{GS} = 0 \text{ V}, I_D = 250 \mu\text{A}$	250			V
ΔBV_{DSS} / ΔT_{J}	Breakdown Voltage Temperature Coefficient	I_D = 250 μ A, Referenced to 25°C		0.28		V/°C
I _{DSS}	Zana Cata Valtana Duain Comment	V _{DS} = 250 V, V _{GS} = 0 V			10	μА
Zero Gate Voltage Drain Current	V _{DS} = 200 V, T _C = 125°C			100	μА	
I _{GSSF}	Gate-Body Leakage Current, Forward	V _{GS} = 30 V, V _{DS} = 0 V			100	nΑ
I _{GSSR}	Gate-Body Leakage Current, Reverse	$V_{GS} = -30 \text{ V}, V_{DS} = 0 \text{ V}$			-100	nA
On Cha	racteristics					
V _{GS(th)}	Gate Threshold Voltage	$V_{DS} = V_{GS}, I_{D} = 250 \mu A$	2.0		4.0	V
R _{DS(on)}	Static Drain-Source On-Resistance	V _{GS} = 10 V, I _D = 31 A		0.029	0.035	Ω
9 _{FS}	Forward Transconductance	V _{DS} = 40 V, I _D = 31 A		55		S
Dynam	ic Characteristics					
C _{iss}	Input Capacitance	V _{DS} = 25 V, V _{GS} = 0 V, f = 1.0 MHz		4830	6280	pF
C _{oss}	Output Capacitance			945	1230	pF
C _{rss}	Reverse Transfer Capacitance			63.5	83	pF
						ы
Switch	ing Characteristics					рі
	ing Characteristics Turn-On Delay Time	Von = 125 V In = 62 A		75	160	ns
Switch t _{d(on)} t _r		$V_{DD} = 125 \text{ V}, I_{D} = 62 \text{ A},$ $R_{C} = 25 \Omega$		75 395	160 800	
$t_{d(on)}$	Turn-On Delay Time	$R_G = 25 \Omega$				ns
$t_{d(on)}$ t_r $t_{d(off)}$	Turn-On Delay Time Turn-On Rise Time	00 . 0		395	800	ns
$t_{d(on)}$ t_r $t_{d(off)}$	Turn-On Delay Time Turn-On Rise Time Turn-Off Delay Time	$R_G = 25 \Omega$	 	395 245	800 500	ns ns
$\begin{array}{c} t_{d(on)} \\ t_{r} \\ \\ t_{d(off)} \\ \end{array}$	Turn-On Delay Time Turn-On Rise Time Turn-Off Delay Time Turn-Off Fall Time	$R_G = 25 \Omega$ (Note 4)		395 245 335	800 500 680	ns ns ns

Drain-Source Diode Characteristics and Maximum Ratings

I _S	Maximum Continuous Drain-Source Diode Forward Current				62	Α
I _{SM}	Maximum Pulsed Drain-Source Diode Forward Current				248	Α
V _{SD}	Drain-Source Diode Forward Voltage	V _{GS} = 0 V, I _S = 62 A	-		1.5	V
t _{rr}	Reverse Recovery Time	$V_{GS} = 0 \text{ V, } I_{S} = 62 \text{ A,}$	-	340		ns
Q _{rr}	Reverse Recovery Charge	dI _F / dt = 100 A/μs		4.77	/	μС

- **Notes:** 1. Repetitive rating: pulse-width limited by maximum junction temperature. 2. L = 0.96 mH, I_{AS} = 62 A, V_{DD} = 50 V, R_G = 25 Ω , starting T_J = 25°C. 3. $I_{SD} \le$ 62 A, di/dt \le 300 A/ μ s, $V_{DD} \le$ BV $_{DSS}$, starting T_J = 25°C. 4. Essentially independent of operating temperature.

Typical Performance Characteristics

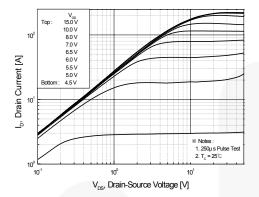


Figure 1. On-Region Characteristics

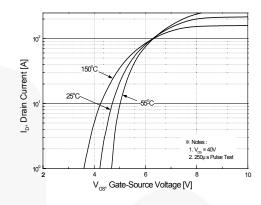


Figure 2. Transfer Characteristics

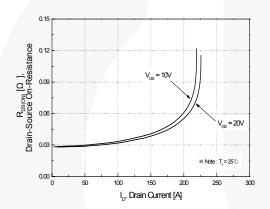


Figure 3. On-Resistance Variation vs Drain Current and Gate Voltage

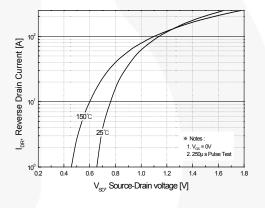


Figure 4. Body Diode Forward Voltage Variation with Source Current and Temperature

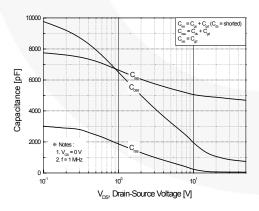


Figure 5. Capacitance Characteristics

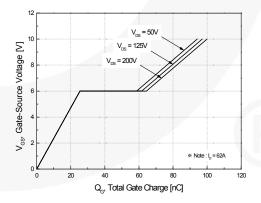


Figure 6. Gate Charge Characteristics

Typical Performance Characteristics (Continued)

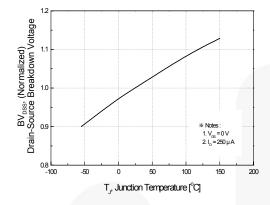


Figure 7. Breakdown Voltage Variation vs Temperature

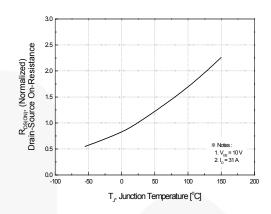


Figure 8. On-Resistance Variation vs Temperature

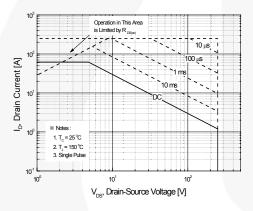


Figure 9. Maximum Safe Operating Area

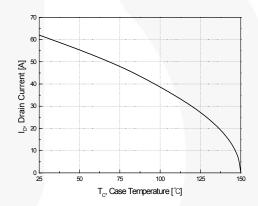


Figure 10. Maximum Drain Current vs Case Temperature

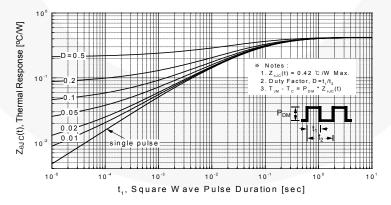


Figure 11. Transient Thermal Response Curve

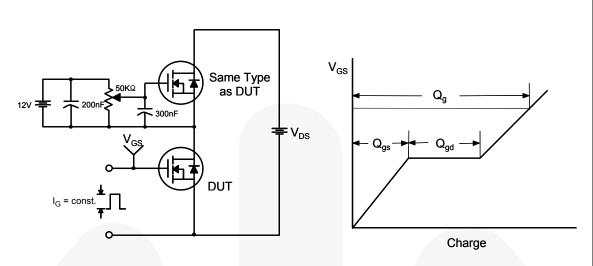


Figure 12. Gate Charge Test Circuit & Waveform

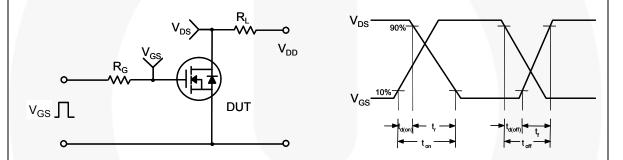


Figure 13. Resistive Switching Test Circuit & Waveforms

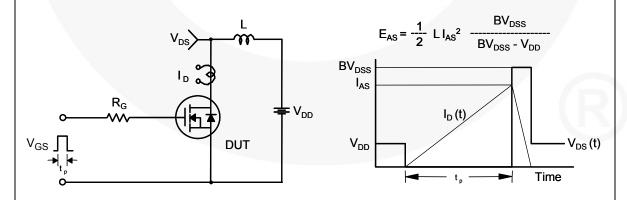
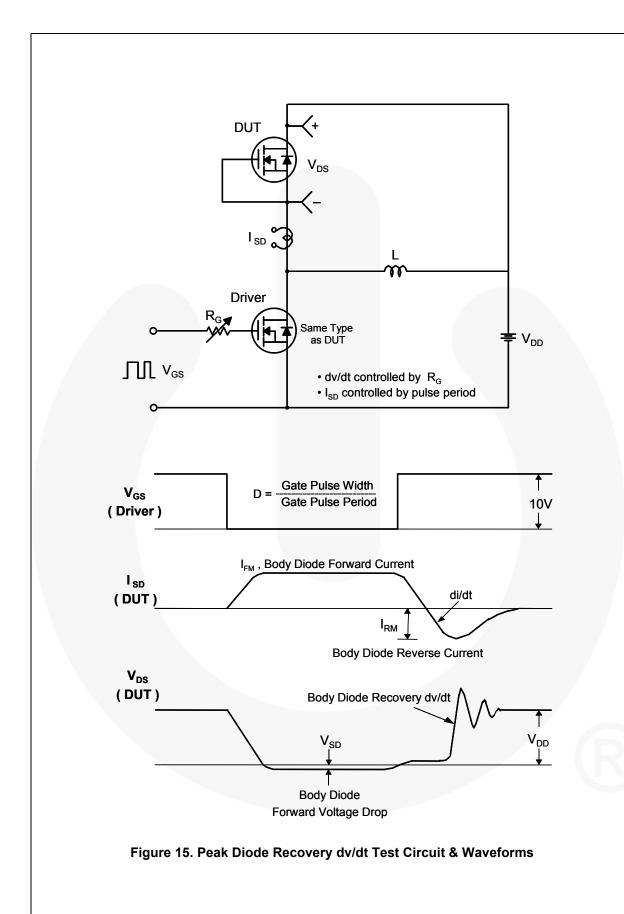


Figure 14. Unclamped Inductive Switching Test Circuit & Waveforms



Mechanical Dimensions

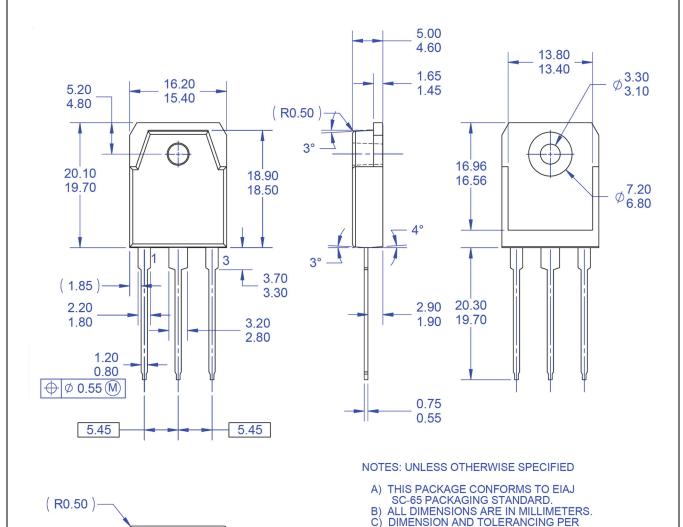


Figure 16. TO3PN, 3-Lead, Plastic, EIAJ SC-65

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E) DRAWING FILE NAME: TO3PN03AREV1.

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